

APPROVAL SHEET

Approval Specification	Customer's Approval Certificate
TO:	Please return this copy as a certification of your approval
Part No.:	Checked & Approved by:
Customer's Part No.:	Date:

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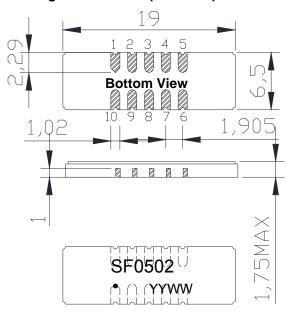
Application

- Low -loss SAW component
- Low amplitude ripple
- Sharp rejections at both out-bands

Features

- Ceramic Package for Surface Mounted Technology (SMT)
- RoHS compatible
- Package size 19.00x6.50x1.75mm³
- Package Code SMD19
- Electrostatic Sensitive Device(ESD)

Package Dimensions (Unit: mm)



Test Circuit(Bottom View)

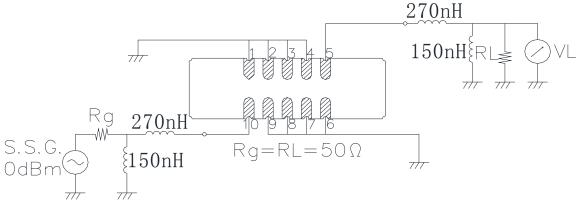
Pin Configuration

Pin No.	Description
10	Input
5	Output
1,2,3,4,6,7,8,9	Ground

Marking Description

S	Trademark	
F	SAW Filter	
0502	Part Number	
•	Pin 1	
YYWW	Year Code & Week Code	

*Fig: If the products produced in 06th week of 2012, The year code & week code is 1206.



Please read notes at the end of this document.

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Performance

Maximum Rating

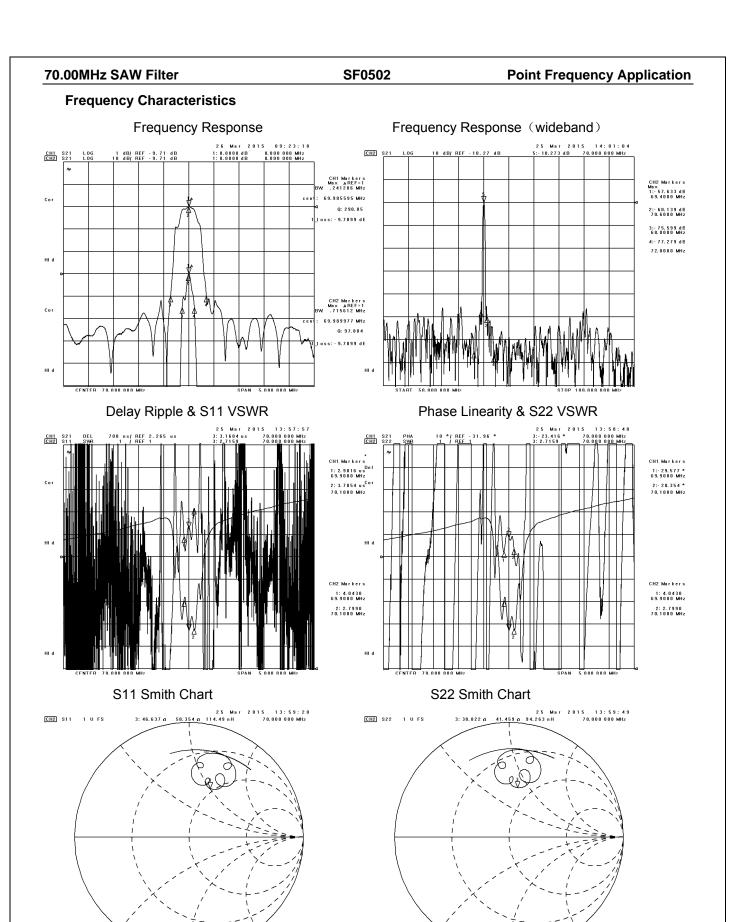
Item		Value	Unit
DC Voltage	V_{DC}	3	V
Operation Temperature	Т	-20~+70	$^{\circ}$
Storage Temperature	T _{stg}	-55 ~ +125	$^{\circ}$
RF Power Dissipation	Р	10	dBm

Electronic Characteristics

Test Temperature: $25^{\circ}C \pm 2^{\circ}C$

Terminating source impedance: 50Ω Terminating load impedance: 50Ω

Item		Minimum	Typical	Maximum	Unit
Center Frequency	fc		70.00		MHz
Insertion Loss(min)	IL		9.7	10.0	dB
Absolute Attenuation	а				
68.00-69.40MHz		40.0	42.0		dB
70.60-72.00MHz		40.0	44.0		dB



SPAN 5.000 000 MHz

CENTER 70.000 000 MHz

CENTER 70.000 000 MHz

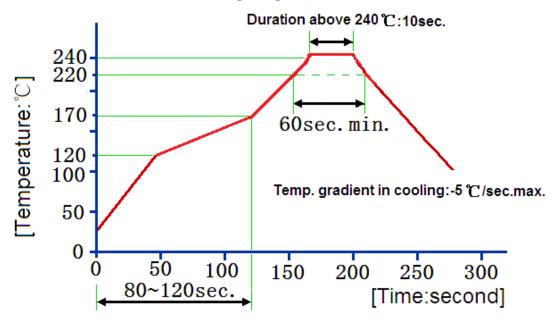
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SPAN 5.000 000 MHz

Reliability (The SAW components shall remain electrical performance after tests)

No.	Test item	Test condition		
1	Temperature	(1) Temperature: 85℃±2℃ , Duration: 250h , Recovery time: 2h±0.5h		
!	Storage	(2) Temperature: −55°C±3°C , Duration: 250h ,Recovery time: 2h±0.5h		
2	Humidity Test	Conditions: 60℃±2℃, 90~95% RH Duration: 250h		
3	Thermal Shock	Heat cycle conditions: TA=-55°C±3°C, TB=85°C±2°C, t1=t2=30min, Switch		
3	Thermal Shock	time: ≤3min, Cycle time: 100 times, Recovery time: 2h±0.5h.		
4	4 Vibration Fatigue	Frequency of vibration: 10~55Hz Amplitude:1.5mm		
		Directions: X,Y and Z Duration: 2h		
5	Drop Test	Cycle time: 10 times Height: 1.0m		
		Temperature: 245 ℃ ±5 ℃ Duration: 3.0s5.0s		
6	Solder Ability Test	Depth: DIP2/3 , SMD1/5		
		(1)Thickness of PCB:1mm , Solder condition: 260 ℃±5 ℃ , Duration: 10±1s		
7	Resistance to Soldering Heat	(2)Temperature of Soldering Iron: 350℃±10℃,Duration: 3~4s,		
		Recovery time: 2 ± 0.5h		

Recommended Reflow Soldering Diagram



Reflow cycles:3 cycles max.

Notes

- 1. As a result of the particularity of inner structure of SAW products, it easy to be breakdown by electrostatic, so we should pay attention to **ESD protect** in the test.
- 2. **Static voltage** between signal load and ground may cause deterioration and destruction of the component. Please avoid static voltage.
- 3. **Ultrasonic cleaning** may cause deterioration and destruction of the component. Please avoid ultrasonic cleaning.
- 4. Only leads of component may be soldered. Please avoid soldering another part of component.
- 5. There is a close relationship between the device's performance and **matching network**. The specifications of this device are based on the test circuit shown above. L and C values may change depending on board layout. Values shown are intended as a guide only.